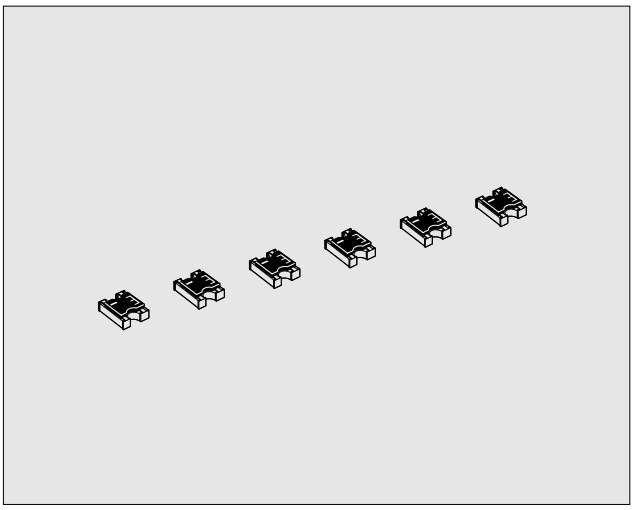
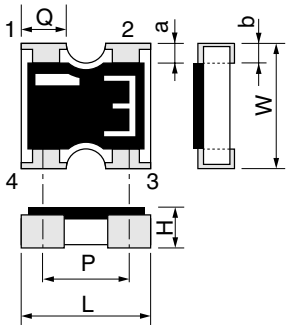
RAC101A

●Features

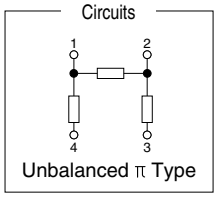
1. Suitable for use at DC and up to UHF band frequencies.
2. Replaceable three discrete resistors with one chip on attenuation circuits.
3. Please contact KAMAYA for Halogen and Antimony free product of RAC101A.



●Dimensions and Circuits



Dot mark on Termination 1
Attenuation factor on Termination 2 to 3



Unit : mm

Style	Terminal Style	L	W	H	Q	a	b	*P	*Unit weight/pc.
RAC101A	**C**	1.0±0.05	1.0±0.05	0.35±0.05	0.33±0.10	0.15±0.10	$0.25^{+0.05}_{-0.10}$	0.65	1.1mg

*Values for reference

●Part Number Description

Example

Style: RAC | 10 | 1 | A

Product Type
RAC

Characteristic Impedance	
1	50 ohm

Size	
10	W:1.0mm

Circuits	
A	Unbalanced πType

1

Attenuation Factor	
0	0dB
X	0.5dB
1	1dB
Y	1.5dB
2	2dB
3	3dB
4	4dB
5	5dB
6	6dB
7	7dB
8	8dB
9	9dB
A	10dB
B	11dB
C	12dB
D	13dB
E	14dB
F	15dB
G	16dB
H	17dB
J	18dB
K	19dB
L	20dB

C

Terminal Style		
C	Convex Type	With corner

TH

* Packaging & Standard Qty. (Min.)		
B	Bulk (Loose Package)	1,000pcs.
TH	Paper Tape (2 mm pitch)	10,000pcs.

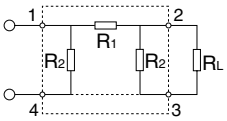
*Refer to Tape and Packaging information on pages 54 and 55.

●Ratings

Style	Characteristic Impedance	Attenuation Factor symbol	Attenuation Factor dB	Tolerance on Attenuation Factor dB	Voltage Standing Wave Ratio	Frequency Range	Rated Input Power mW/package	Category Temperature Range °C
RAC101A	—	0	0	—	—	—	100	–40~+125
	50 ohm	X	0.5	±0.1	1.1max.	DC ≤f ≤3GHz		
		1	1	±0.3	1.2max.			
		Y	1.5					
		2	2					
		3	3					
		4	4					
		5	5					
		6	6	±0.4				
		7	7					
		8	8					
		9	9					
		A	10					
		B	11	±0.8				
		C	12					
		D	13					
		E	14	±1.0				
		F	15	±1.5				
		G	16					
		H	17	±2.0				
		J	18					
		K	19					
		L	20	±2.5				

Note. The following information is available.
1. Test methods for Attenuation Factor and VSWR characteristics.

●Performance Characteristics JIS C 5201-1 : 1998

Description	Requirements 0.5~2dB	Requirements 3dB~5dB	Requirements 6dB~20dB	Test Methods
Characteristic impedance	50 ohm			Measuring Circuits  R_L=50 ohm
Insulation resistance	At least 100M ohm			50Vd.c., 60s
Solderability	In accordance with Clause 4.17.4.5			Clause 4.17 Dip into 235°C Solder bath for 2s.
Resistance to soldering heat	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.18 Dip into 260°C Solder bath for 5s.
	No major visible damage.			
Rapid change of temperature	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.19 5 cycles between –55°C and +125°C.
	No major visible damage.			
Endurance at 85˚C	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.25.1 Rated input power, 1.5h"ON", 0.5h"OFF", 85°C, 1,000h.
Bend strength of the face plating	Within ±0.1dB	Within ±0.2dB	Within ±0.3dB	Clause 4.33 Amount of bend : 3 mm